

PowerMOS transistor

GENERAL DESCRIPTION

N-channel enhancement mode field-effect power transistor in a plastic full pack envelope.

The device is intended for use in Switched Mode Power Supplies (SMPS), motor control, welding, DC/DC and AC/DC converters, and in general purpose switching applications.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{DS}	Drain-source voltage	450	V
I_D	Drain current (DC)	5.6	A
P_{tot}	Total power dissipation	45	W
$R_{DS(ON)}$	Drain-source on-state resistance	0.6	Ω

MECHANICAL DATA

Dimensions in mm

Net Mass: 5.5 g

Pinning:

1 = Gate

3 = Source

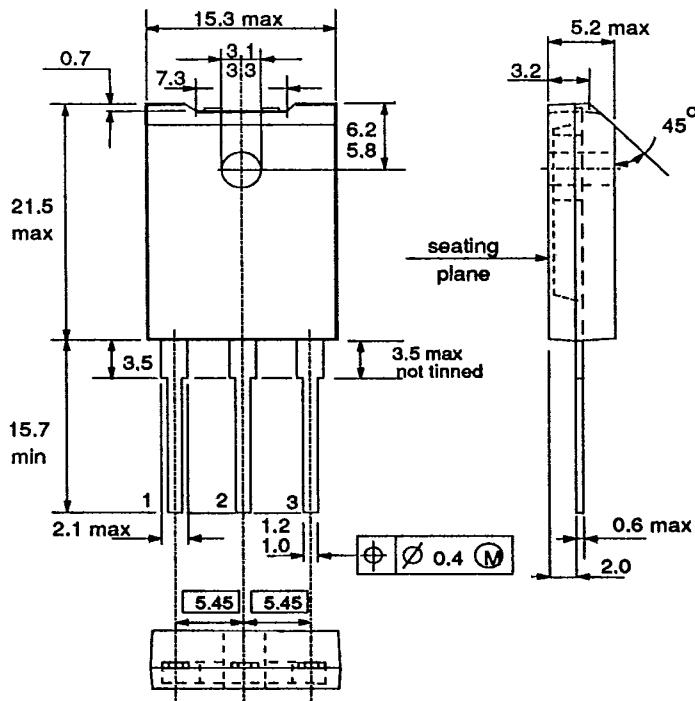
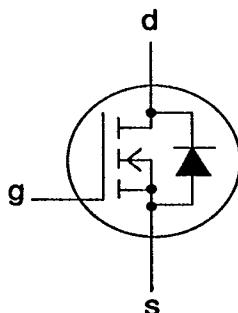


Fig.1 SOT-199; The seating plane is electrically isolated from all terminals.

Notes

1. Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
 2. Accessories supplied on request: refer to Mounting instructions for F-pack envelopes.

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RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS}	Drain-source voltage	-	-	450	V
V_{DGR}	Drain-gate voltage	$R_{GS} = 20 \text{ k}\Omega$	-	450	V
$\pm V_{GS}$	Gate-source voltage	-	-	30	V
I_D	Drain current (DC)	$T_{hs} = 25^\circ\text{C}$	-	5.6	A
I_D	Drain current (DC)	$T_{hs} = 100^\circ\text{C}$	-	3.5	A
I_{DM}	Drain current (pulse peak value)	$T_{hs} = 25^\circ\text{C}$	-	22	A
P_{tot}	Total power dissipation	$T_{hs} = 25^\circ\text{C}$	-	45	W
T_{stg}	Storage temperature	-	-55	150	'C
T_J	Junction Temperature	-	-	150	'C

THERMAL RESISTANCES

From junction to heatsink	with heatsink compound	$R_{th,j-hs} = 2.8 \text{ K/W}$
From junction to ambient	-	$R_{th,j-a} = 35 \text{ K/W}$

STATIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.25 \text{ mA}$	450	-	-	V
$V_{GS(TO)}$	Gate threshold voltage	$V_{DS} = V_{GS}; I_D = 1 \text{ mA}$	2.1	3.0	4.0	V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 450 \text{ V}; V_{GS} = 0 \text{ V}; T_J = 25^\circ\text{C}$	-	2	20	μA
I_{GSS}	Zero gate voltage drain current	$V_{DS} = 450 \text{ V}; V_{GS} = 0 \text{ V}; T_J = 125^\circ\text{C}$	-	0.1	1.0	mA
$R_{DS(ON)}$	Gate source leakage current	$V_{GS} = \pm 30 \text{ V}; V_{DS} = 0 \text{ V}$	-	10	100	nA
	Drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 6.5 \text{ A}$	-	0.55	0.6	Ω

DYNAMIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
g_{fs}	Forward transconductance	$V_{DS} = 25 \text{ V}; I_D = 6.5 \text{ A}$	5.0	8.0	-	S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Feedback capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	1500	1800	pF
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Turn-on rise time Turn-off delay time Turn-off fall time	$V_{DD} = 30 \text{ V}; I_D = 2.8 \text{ A}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega; R_{gen} = 50 \Omega$	-	20	40	ns
t_r			-	60	90	ns
$t_{d(off)}$			-	200	250	ns
t_f			-	75	90	ns
L_d	Internal drain inductance	Measured from drain lead 6 mm from package to centre of die	-	5	-	nH
L_s	Internal source inductance	Measured from source lead 6 mm from package to source bond pad	-	12.5	-	nH

ISOLATION $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	Repetitive peak voltage from all three terminals to external heatsink	R.H. $\leq 65\%$; clean and dustfree	-	-	2500	V
C_{isol}	Capacitance from T2 to external heatsink	$f = 1 \text{ MHz}$	-	22	-	pF

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REVERSE DIODE RATINGS AND CHARACTERISTICS

 $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{DR}	Continuous reverse drain current	-	-	-	5.6	A
I_{DM}	Pulsed reverse drain current	-	-	-	22	A
V_{SD}	Diode forward voltage	$I_F = 5.6 \text{ A}; V_{GS} = 0 \text{ V}$	-	1.1	1.4	V
t_{rr}	Reverse recovery time	$I_F = 5.6 \text{ A}; -dI_F/dt = 100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V}$	-	500	-	ns
Q_{rr}	Reverse recovery charge	$V_{GS} = 0 \text{ V}; V_R = 100 \text{ V}$	-	6.0	-	μC

AVALANCHE RATING

 $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
W_{DSS}	Drain-source non-repetitive unclamped inductive turn-off energy	$I_D = 10 \text{ A}; V_{DD} \leq 250 \text{ V}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega$	-	-	500	mJ

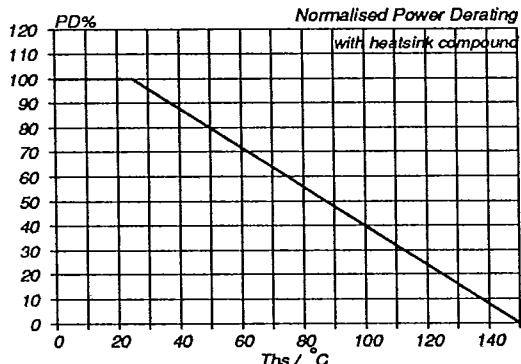


Fig.2. Normalised power dissipation.
 $PD\% = 100 \cdot P_D/P_{D, 25^\circ\text{C}} = f(T_{hs})$

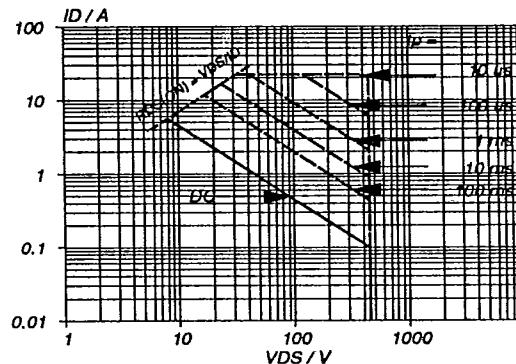


Fig.4. Safe operating area. $T_{hs} = 25^\circ\text{C}$
 I_D & $I_{DM} = f(V_{DS})$; I_{DM} single pulse; parameter t_p

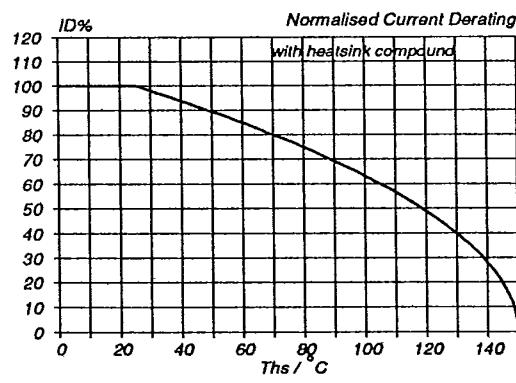


Fig.3. Normalised continuous drain current.
 $ID\% = 100 \cdot I_D/I_{D, 25^\circ\text{C}} = f(T_{hs})$; conditions: $V_{GS} \geq 10 \text{ V}$

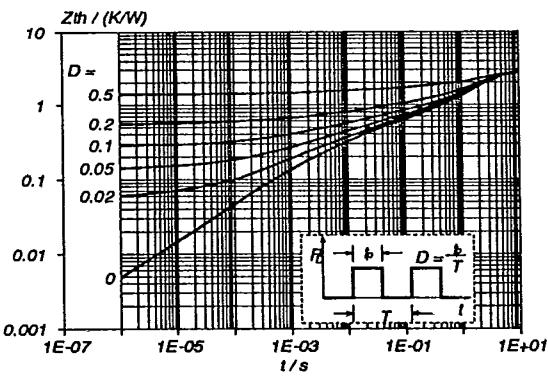


Fig.5. Transient thermal impedance.
 $Z_{th, hs} = f(t)$; parameter $D = t_p/T$

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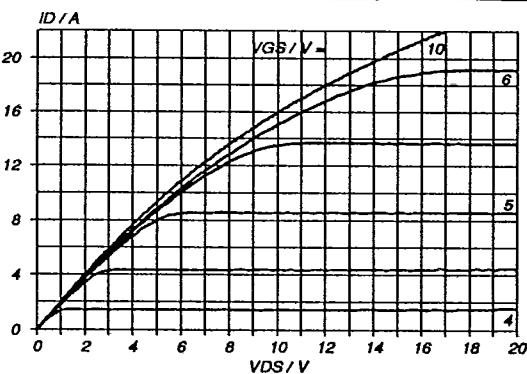


Fig. 6.¹ Typical output characteristics, $T_J = 25^\circ\text{C}$.
 $I_D = f(V_{DS})$; parameter V_{GS}

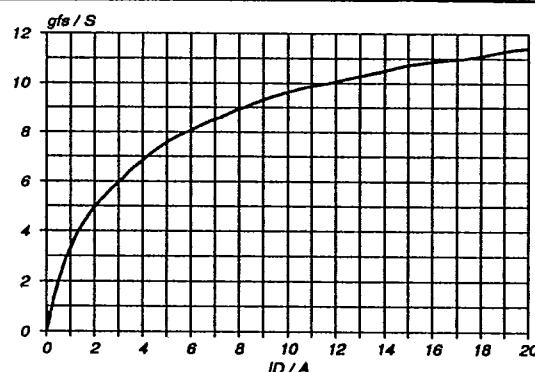


Fig. 9. Typical transconductance, $T_J = 25^\circ\text{C}$.
 $g_{fs} = f(I_D)$; conditions: $V_{DS} = 25\text{ V}$

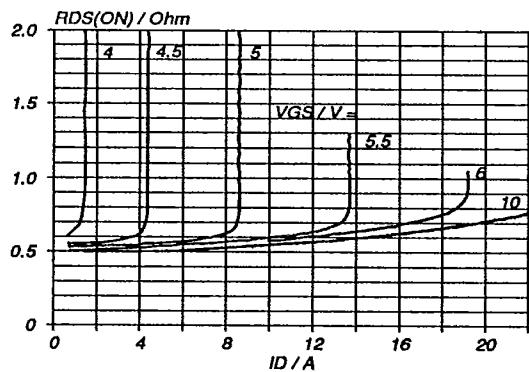


Fig. 7. Typical on-state resistance, $T_J = 25^\circ\text{C}$.
 $R_{DS(ON)} = f(I_D)$; parameter V_{GS}

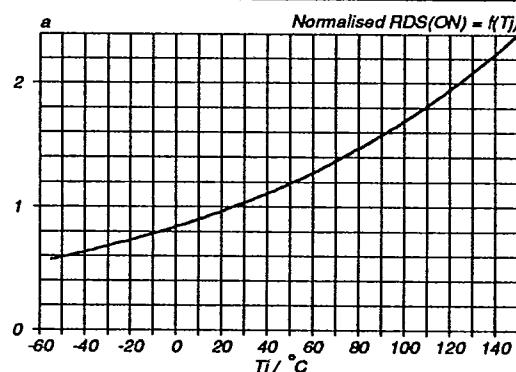


Fig. 10. Normalised drain-source on-state resistance.
 $a = R_{DS(ON)}/R_{DS(ON)25^\circ\text{C}} = f(T_J)$; $I_D = 6.5\text{ A}$; $V_{GS} = 10\text{ V}$

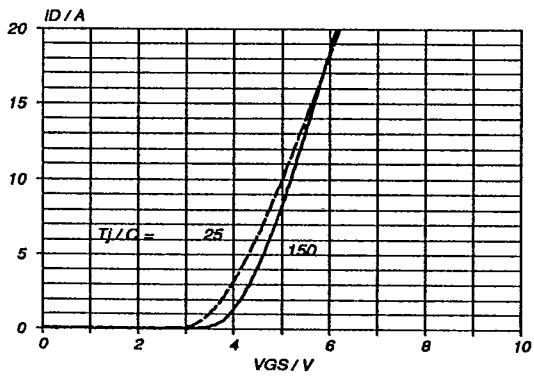


Fig. 8. Typical transfer characteristics.
 $I_D = f(V_{GS})$; conditions: $V_{DS} = 25\text{ V}$; parameter T_J

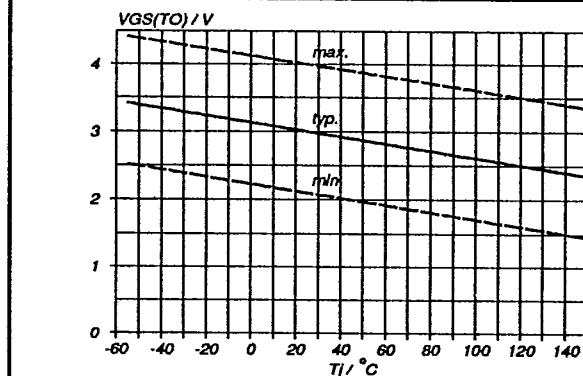


Fig. 11. Gate threshold voltage.
 $V_{GS(TO)} = f(T_J)$; conditions: $I_D = 1\text{ mA}$; $V_{DS} = V_{GS}$

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